# **2-Input NOR Gate**

The NL17SZ02 is a single 2-input NOR Gate in two tiny footprint packages. The device performs much as LCX multi-gate products in speed and drive.

### Features

- Tiny SOT-353 and SOT-553 Packages
- 2.4 ns T<sub>PD</sub> at 5 V (typ)
- Source/Sink 24 mA at 3.0 V
- Over-Voltage Tolerant Inputs
- Pin For Pin with NC7SZ02P5X, TC7SZ02FU and TC7SZ02AFE
- Chip Complexity: FETs = 20
- Designed for 1.65 V to 5.5 V V<sub>CC</sub> Operation
- These Devices are Pb-Free and are RoHS Compliant
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

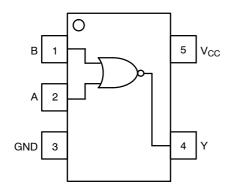


Figure 1. Pinout (Top View)

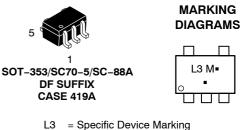


Figure 2. Logic Symbol



# **ON Semiconductor®**

http://onsemi.com



- M = Date Code
- = Pb-Free Package
- (Note: Microdot may be in either location)

<sup>5</sup> 1 SOT-553 XV5 SUFFIX CASE 463B



L3 = Specific Device Marking M = Date Code

#### **PIN ASSIGNMENT**

Pin	Function
1	А
2	В
3	GND
4	Y
5	V <sub>CC</sub>

#### FUNCTION TABLE

Ing	out	Output Y = $\overline{A + B}$
A	В	Y
L	L	н
L	Н	L
н	L	L
Н	Н	L

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

## MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V <sub>CC</sub>	DC Supply Voltage		-0.5 to +7.0	V
V <sub>IN</sub>	DC Input Voltage		-0.5 to +7.0	V
V <sub>OUT</sub>	DC Output Voltage		$-0.5$ to V_CC + 0.5	V
Ι <sub>ΙΚ</sub>	DC Input Diode Current		-50	mA
I <sub>OK</sub>	DC Output Diode Current		-50	mA
I <sub>OUT</sub>	DC Output Sink Current		±50	mA
I <sub>CC</sub>	DC Supply Current per Supply Pin	±100	mA	
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C	
ΤL	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
TJ	Junction Temperature Under Bias		+ 150	°C
$\theta_{JA}$	Thermal Resistance	SOT-353 (Note 1) SOT-553	350 496	°C/W
PD	Power Dissipation in Still Air at 85°C	SOT-353 SOT-553	186 135	mW
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
ESD		Human Body Model (Note 2) Machine Model (Note 3) arged Device Model (Note 4)	Class Z Class A N/A	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.

2. Tested to EIA/JESD22-A114-A, rated to EIA/JESD22-A114-B.

3. Tested to EIA/JESD22-A115-A, rated to EIA/JESD22-A115-A.

4. Tested to JESD22-C101-A.

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter			Max	Unit
V <sub>CC</sub>	DC Supply Voltage		1.65	5.5	V
V <sub>IN</sub>	DC Input Voltage		0	5.5	V
V <sub>OUT</sub>	DC Output Voltage		0	5.5	V
T <sub>A</sub>	Operating Temperature Range		-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time $$V_{CC}$$ : $$V_{CC}$$ :	= 3.0 V ±0.3 V = 5.0 V ±0.5 V	0 0	100 20	ns/V

DC ELECTRICAL C	HARACTERISTICS
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			V <sub>cc</sub>	T <sub>A</sub> = 25°C			$-55^{\circ}C  \leq  T_{A}  \leq  125^{\circ}C$		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
V <sub>IH</sub>	High-Level Input Voltage		1.65 to 1.95 2.3 to 5.5	0.75 V <sub>CC</sub> 0.7 V <sub>CC</sub>			0.75 V <sub>CC</sub> 0.7 V <sub>CC</sub>		V
V <sub>IL</sub>	Low-Level Input Voltage		1.65 to 1.95 2.3 to 5.5			0.25 V <sub>CC</sub> 0.3 V <sub>CC</sub>		0.25 V <sub>CC</sub> 0.3 V <sub>CC</sub>	V
V <sub>OH</sub>	High–Level Output Voltage V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub>	$\begin{split} I_{OH} &= 100 \; \mu A \\ I_{OH} &= -3 \; m A \\ I_{OH} &= -8 \; m A \\ I_{OH} &= -12 \; m A \\ I_{OH} &= -16 \; m A \\ I_{OH} &= -24 \; m A \\ I_{OH} &= -32 \; m A \end{split}$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5	$\begin{array}{c} V_{CC} - 0.1 \\ 1.29 \\ 1.9 \\ 2.2 \\ 2.4 \\ 2.3 \\ 3.8 \end{array}$	V <sub>CC</sub> 1.52 2.1 2.4 2.7 2.5 4.0		V <sub>CC</sub> - 0.1 1.29 1.9 2.2 2.4 2.3 3.8		V
V <sub>OL</sub>	Low-Level Output Voltage V <sub>IN</sub> = V <sub>IH</sub> or V <sub>OH</sub>	$I_{OL} = 100 \ \mu A$ $I_{OL} = 3 \ m A$ $I_{OL} = 8 \ m A$ $I_{OL} = 12 \ m A$ $I_{OL} = 16 \ m A$ $I_{OL} = 24 \ m A$ $I_{OL} = 32 \ m A$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5		0.08 0.20 0.22 0.28 0.38 0.42	0.1 0.24 0.3 0.4 0.4 0.55 0.55		0.1 0.24 0.3 0.4 0.4 0.55 0.55	V
I <sub>IN</sub>	Input Leakage Current	$V_{IN}$ = 5.5 V or GND	0 to 5.5			±0.1		±1.0	μA
I <sub>OFF</sub>	Power Off Leakage Current	$V_{IN} = 5.5 V \text{ or}$ $V_{OUT} = 5.5 V$	0			1		10	μΑ
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> = 5.5 V or GND	5.5			1		10	μΑ

## AC ELECTRICAL CHARACTERISTICS $t_{R}$ = $t_{F}$ = 3.0 ns

			V <sub>CC</sub>	T <sub>A</sub> = 25°C		$\text{-55°C} \leq \text{T}_{\text{A}} \leq 125^{\circ}\text{C}$			
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Мах	Unit
t <sub>PLH</sub>	Propagation Delay	$R_L$ = 1 M $\Omega$ , $C_L$ = 15 pF	1.65	2.0	5.3	11.5	2.0	12.0	ns
t <sub>PHL</sub>	(Figure 3 and 4)	$R_L$ = 1 M $\Omega$ , $C_L$ = 15 pF	1.8	2.0	4.4	9.5	2.0	10.0	
		$R_L$ = 1 M $\Omega$ , $C_L$ = 15 pF	$2.5\pm0.2$	0.8	2.9	6.5	0.8	7.0	
		$R_L$ = 1 M $\Omega$ , $C_L$ = 15 pF	$3.3\pm0.3$	0.5	2.3	4.5	0.5	4.7	
		$R_L$ = 500 $\Omega$ , $C_L$ = 50 pF		1.5	2.9	5.0	1.5	5.2	
		$R_L = 1 M\Omega, C_L = 15 pF$	$5.0\pm0.5$	0.5	1.9	3.9	0.5	4.1	
		$R_L$ = 500 $\Omega$ , $C_L$ = 50 pF		0.8	2.4	4.3	0.8	4.5	

### **CAPACITIVE CHARACTERISTICS**

Symbol	Parameter	Condition	Typical	Unit
C <sub>IN</sub>	Input Capacitance	$V_{CC}$ = 5.5 V, $V_I$ = 0 V or $V_{CC}$	>4	pF
C <sub>PD</sub>	Power Dissipation Capacitance	10 MHz, $V_{CC}$ = 3.3 V, $V_I$ = 0 V or $V_{CC}$	25	pF
	(Note 5)	10 MHz, $V_{CC}$ = 5.5 V, $V_I$ = 0 V or $V_{CC}$	30	

5.  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation:  $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$ .  $C_{PD}$  is used to determine the no–load dynamic power consumption;  $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$ .

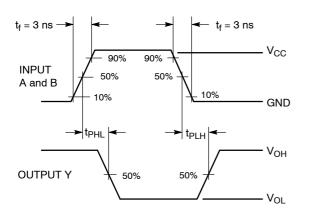
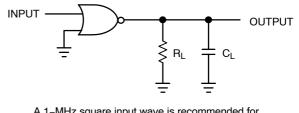


Figure 3. Switching Waveform



A 1–MHz square input wave is recommended for propagation delay tests.



#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NL17SZ02DFT2G	SC-88A/SOT-353/SC-70-5 (Pb-Free)	3000 / Tape & Reel
NLV17SZ02DFT2G*	SC-88A/SOT-353/SC-70-5 (Pb-Free)	3000 / Tape & Reel
NL17SZ02XV5T2G	SOT-553 (Pb-Free)	

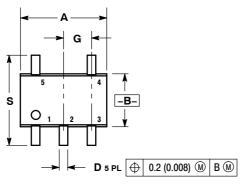
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable.

## NL17SZ02

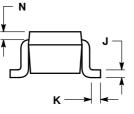
#### **PACKAGE DIMENSIONS**

SOT-353 (SC-88A, SC-70) DF SUFFIX CASE 419A-02 **ISSUE J** 



С

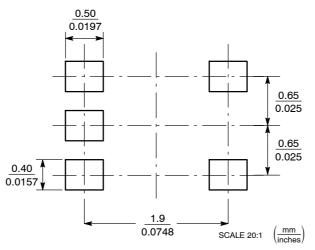
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- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02. 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65	BSC
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
Ν	0.008 REF 0.20 REF			REF
S	0.079	0.087	2.00	2.20

**SOLDERING FOOTPRINT\*** 

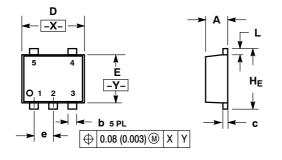


\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### NL17SZ02

#### PACKAGE DIMENSIONS

SOT-553 **XV5 SUFFIX** CASE 463B **ISSUE B** 



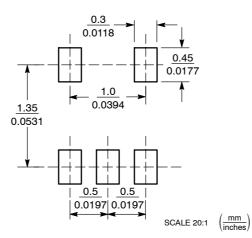
 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
CONTROLLING DIMENSION: MULTIMETERS NOTES

CONTROLLING DIMENSION: MILLIMETERS MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM З.

THICKNESS OF BASE MATERIAL

	MILLIMETERS				INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.50	0.55	0.60	0.020	0.022	0.024
b	0.17	0.22	0.27	0.007	0.009	0.011
С	0.08	0.13	0.18	0.003	0.005	0.007
D	1.50	1.60	1.70	0.059	0.063	0.067
Е	1.10	1.20	1.30	0.043	0.047	0.051
е	0.50 BSC				0.020 BSC	)
Г	0.10	0.20	0.30	0.004	0.008	0.012
ΗE	1.50	1.60	1.70	0.059	0.063	0.067

#### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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